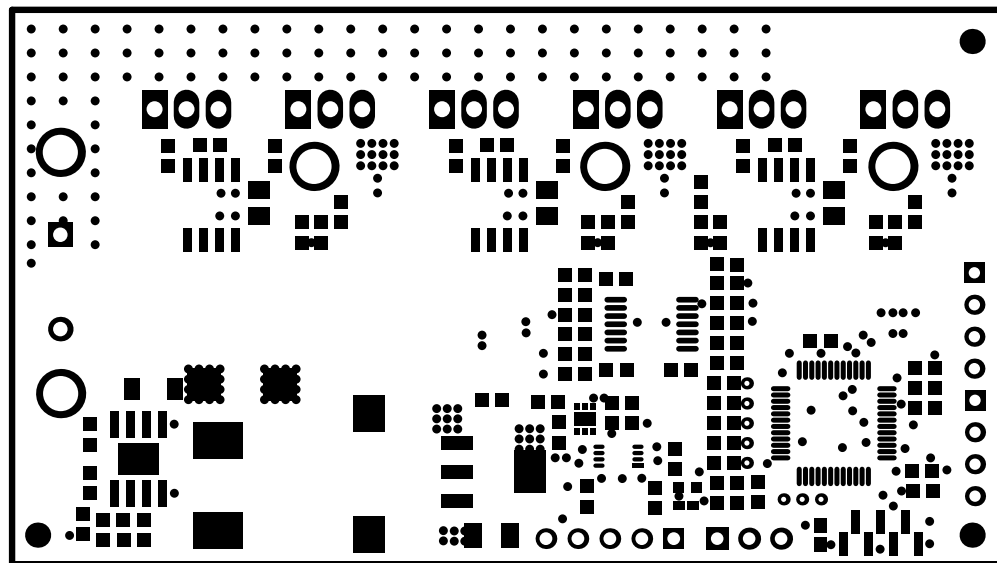
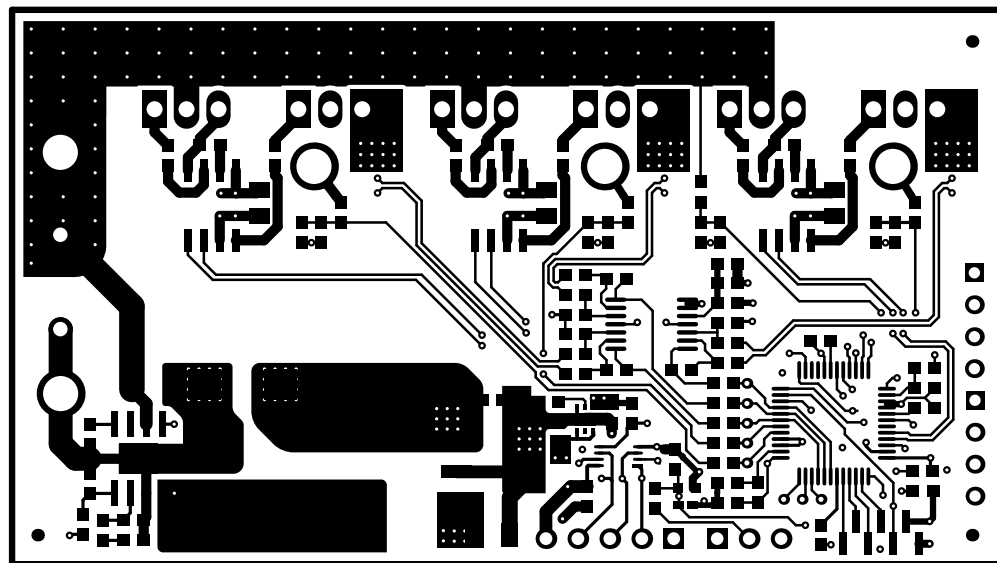


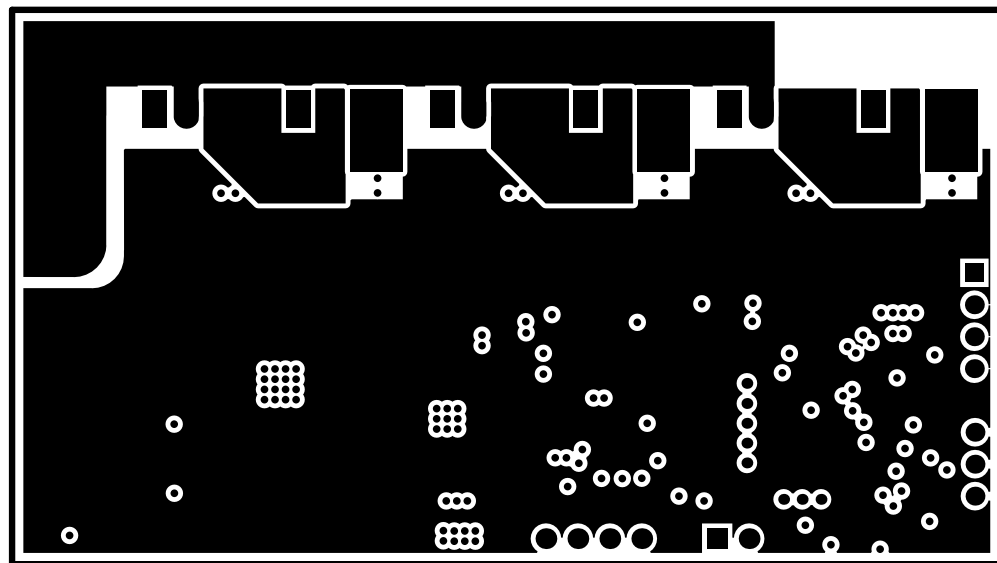
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Overlay	GENERATED : 2/18/2017 8:44:44 PM	TEXAS INSTRUMENTS	



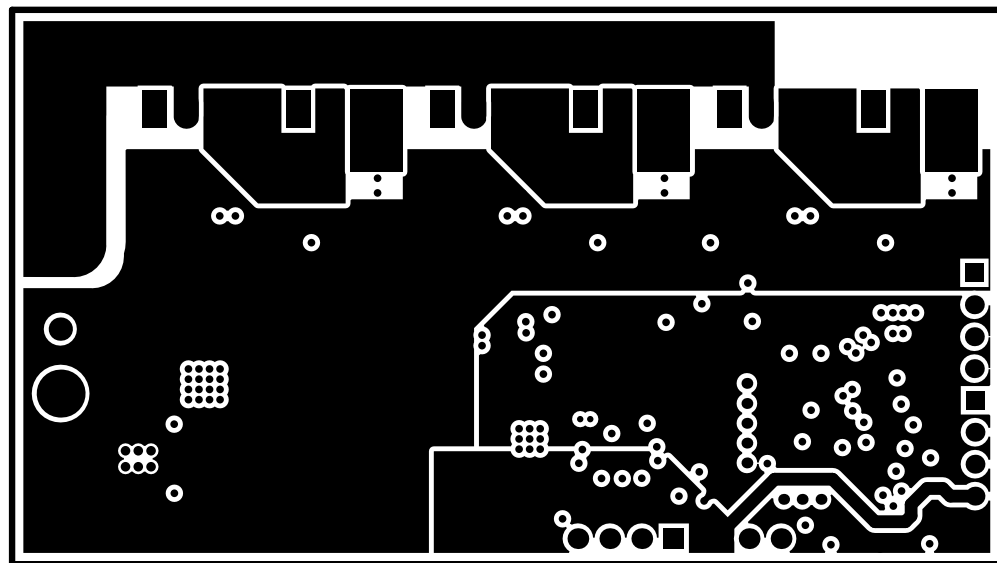
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Solder Mask	GENERATED : 2/18/2017 8:44:46 PM	TEXAS INSTRUMENTS	



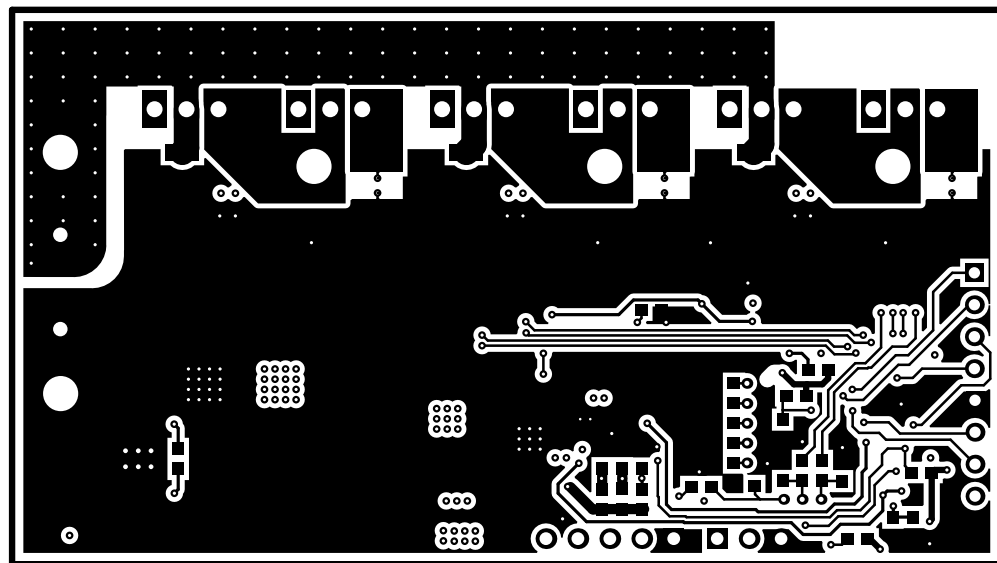
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Top Layer	GENERATED : 2/18/2017 8:44:48 PM	TEXAS INSTRUMENTS	



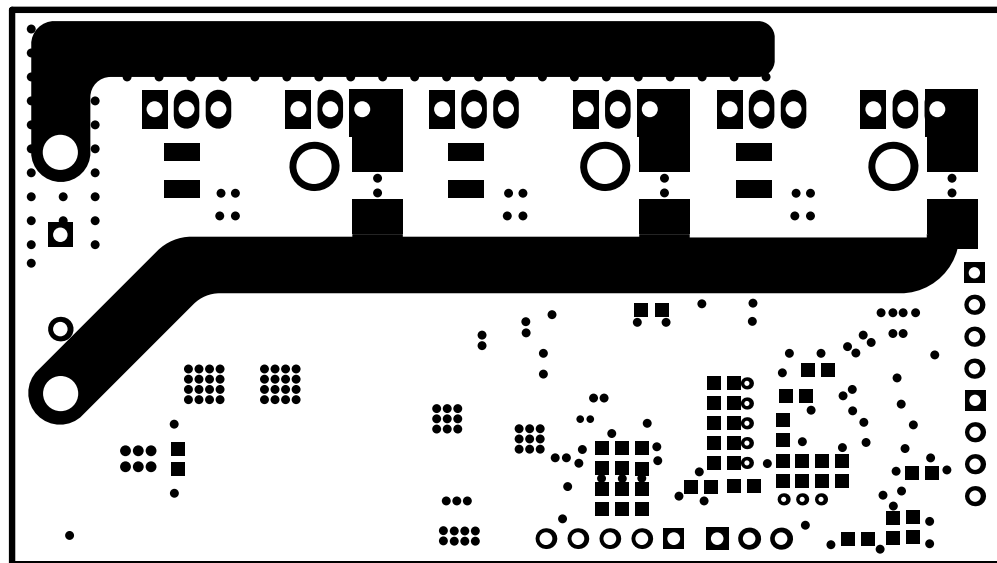
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal 1	GENERATED : 2/18/2017 8:44:50 PM	TEXAS INSTRUMENTS	



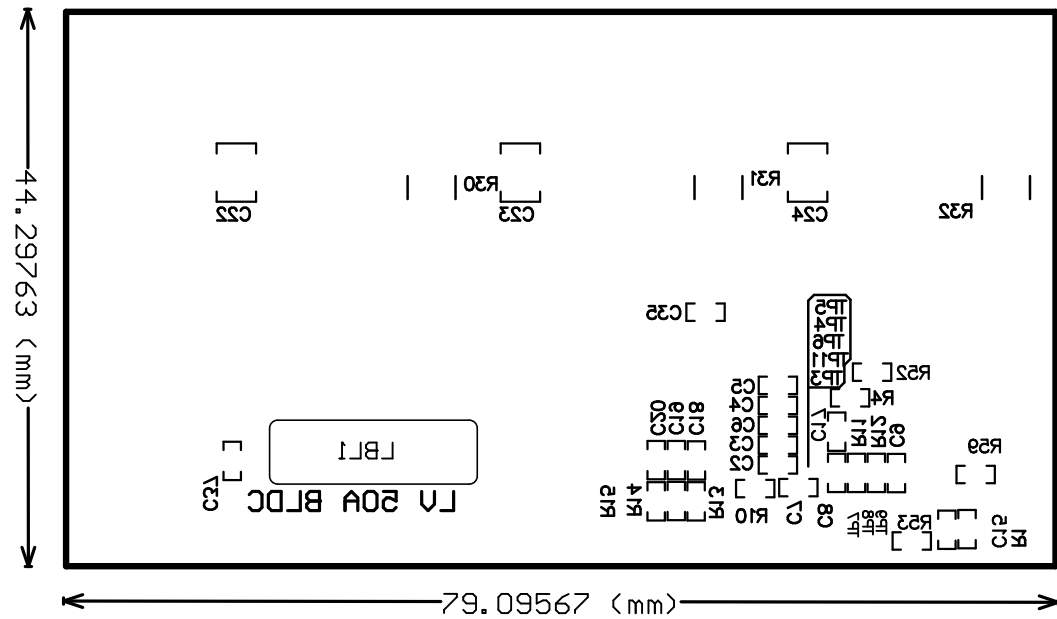
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal 2	GENERATED : 2/18/2017 8:44:52 PM	TEXAS INSTRUMENTS	



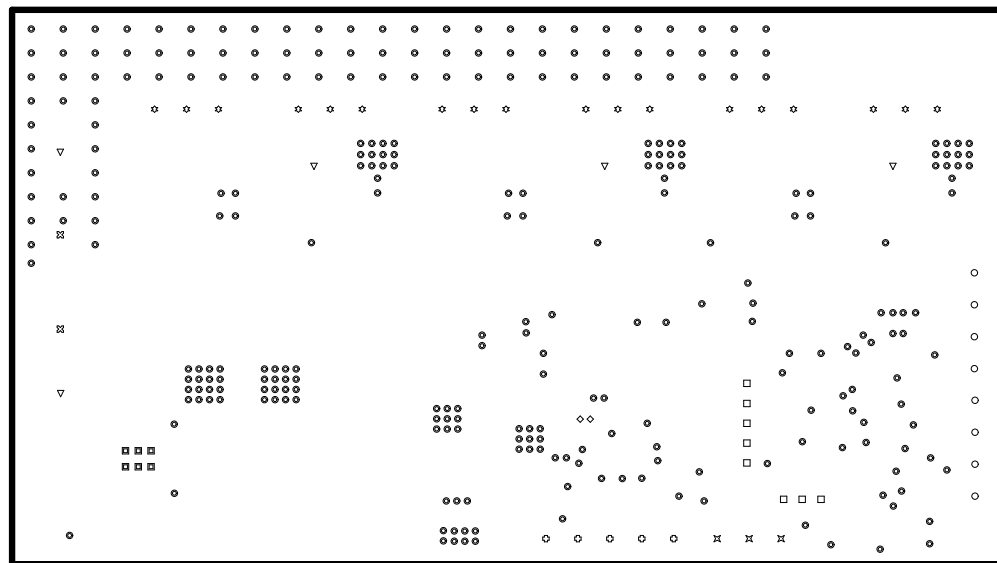
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Layer	GENERATED : 2/18/2017 8:44:53 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/18/2017 8:44:55 PM	TEXAS INSTRUMENTS	

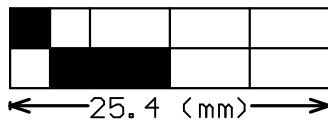


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Bottom Overlay	GENERATED : 2/18/2017 8:44:57 PM	TEXAS INSTRUMENTS	

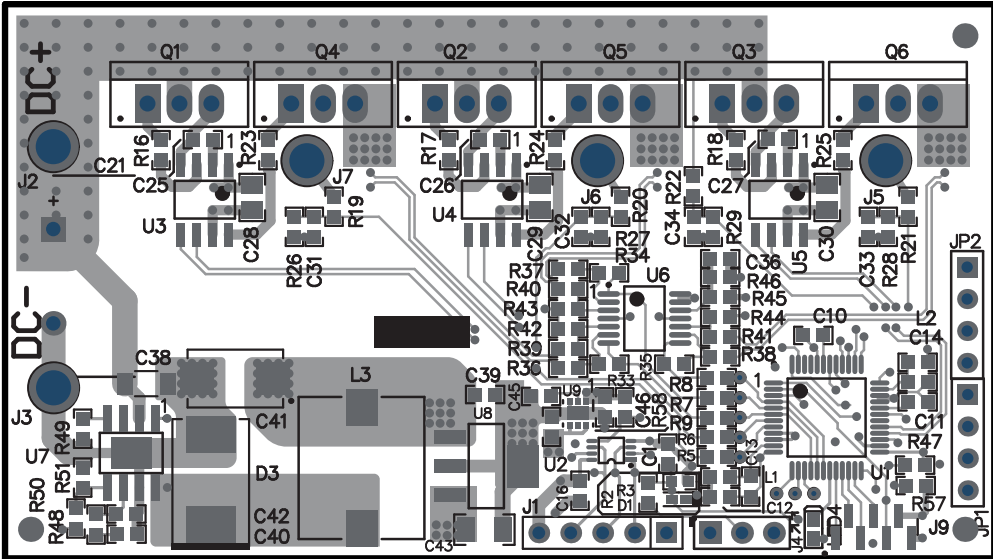


Symbol	Count	Hole Size	Plated	Hole Type
◇	2	0.203mm (8.00mil)	PTH	Round
⊗	2	1.150mm (45.28mil)	PTH	Round
✕	3	1.000mm (39.37mil)	PTH	Round
⊕	5	1.016mm (40.00mil)	PTH	Round
▽	5	2.794mm (110.00mil)	PTH	Round
▣	6	0.381mm (15.00mil)	PTH	Round
□	8	0.406mm (16.00mil)	PTH	Round
○	8	0.900mm (35.43mil)	PTH	Round
☆	18	1.270mm (50.00mil)	PTH	Round
◎	281	0.254mm (10.00mil)	PTH	Round
	338 Total			

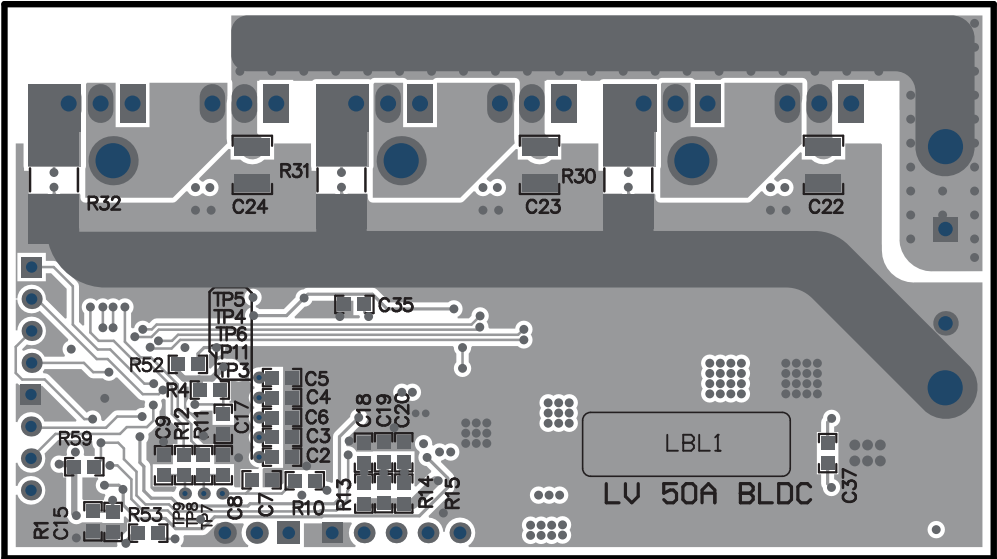
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/18/2017 8:44:59 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDM-1003	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 2/18/2017 8:45:01 PM	TEXAS INSTRUMENTS	



String



44.0 (mm) 100.0

100.0 (mm)

LBL1
LV 50A BLDC

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